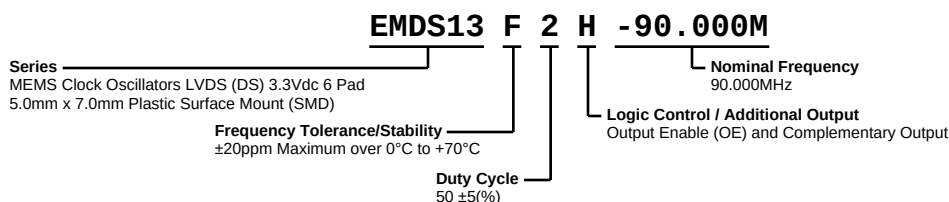


EMDS13F2H-90.000M



ELECTRICAL SPECIFICATIONS

Nominal Frequency	90.000MHz
Frequency Tolerance/Stability	$\pm 20\text{ppm}$ Maximum over 0°C to $+70^{\circ}\text{C}$ (Inclusive of all conditions: Calibration Tolerance at 25°C , Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C , Reflow, Shock, and Vibration)
Aging at 25°C	$\pm 1\text{ppm}$ First Year Maximum
Supply Voltage	$+3.3\text{Vdc} \pm 0.3\text{Vdc}$
Input Current	80mA Maximum (Excluding Load Termination Current)
Output Voltage Logic High (Voh)	1.425Vdc Typical
Output Voltage Logic Low (Vol)	1.075Vdc Typical
Differential Output Voltage (Vod)	247mVdc Minimum, 350mVdc Typical, 454mVdc Maximum
Offset Voltage (Vos)	1.125V Minimum, 1.250V Typical, 1.375V Maximum
Rise/Fall Time	225pSec Typical, 325pSec Maximum (Measured over 20% to 80% of waveform)
Differential Output Error (dVod)	50mVdc Maximum
Duty Cycle	$50 \pm 5(\%)$ (Measured at 50% of waveform)
Offset Error (dVos)	50mVdc Maximum
Load Drive Capability	100 Ohms Between Output and Complementary Output
Output Logic Type	LVDS
Logic Control / Additional Output	Output Enable (OE) and Complementary Output
Output Control Input Voltage	Vih of 70% of Vdd Minimum or No Connect to Enable Output and Complementary Output, Vil of 30% of Vdd Maximum to Disable Output and Complementary Output (High Impedance)
Output Enable Current	75mA Maximum (Without Load)
Period Jitter (Deterministic)	0.2pSec Typical
Period Jitter (Random)	2.0pSec Typical
Period Jitter (RMS)	1.8pSec Typical, 2.5pSec Maximum
Period Jitter (pk-pk)	25pSec Typical, 30pSec Maximum
RMS Phase Jitter (Fj = 637kHz to 10MHz; Random)	2.1pSec Typical
RMS Phase Jitter (Fj = 1MHz to 20MHz; Random)	1.7pSec Typical
RMS Phase Jitter (Fj = 1.875MHz to 20MHz; Random)	1.5pSec Typical
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to $+125^{\circ}\text{C}$

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 2, HBM 2000V
Flammability	UL94-V0
Mechanical Shock	MIL-STD-883, Method 2002, Condition G, 30,000G
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity Level	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003 (Six I/O Pads on bottom of package only)
Temperature Cycling	MIL-STD-883, Method 1010, Condition B

EMDS13F2H-90.000M



Thermal Shock	MIL-STD-883, Method 1011, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A, 20G

[illegible]

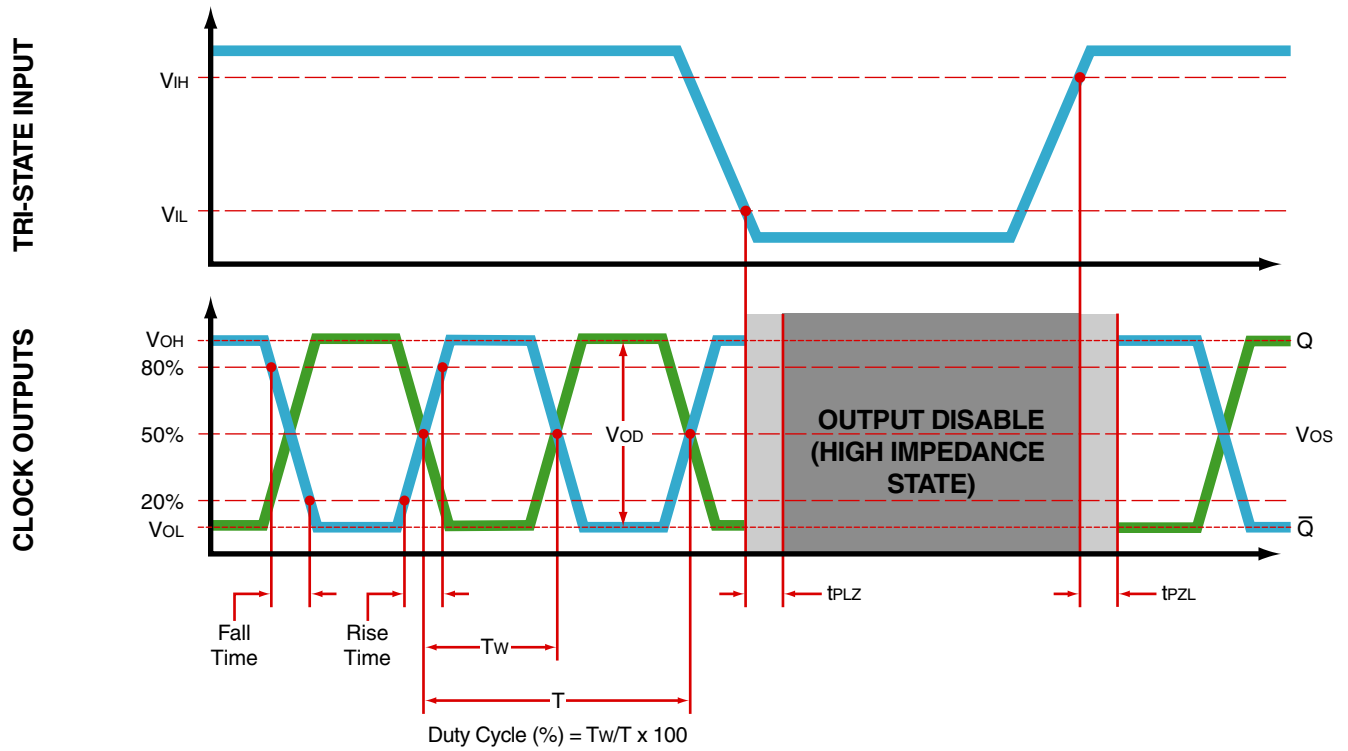
LINE	MARKING
1	XXXX or XXXXX XXXX or XXXXX=Ecliptek Manufacturing Identifier

Figure 1: Dimensions of the test board. The diagram shows a 3x2 grid of blue square components. Dimensions are given in inches and multiplied by a factor in parentheses. Horizontal dimensions: 1.80 (X6) between columns, 2.39 (X6) from the left edge to the first column, and 2.00 (X6) from the second column to the right edge. Vertical dimensions: 0.54 (X4) between rows, and 2.00 (X6) from the top edge to the first row and from the second row to the bottom edge. A label 'Solder Land (X6)' points to the bottom-right component.

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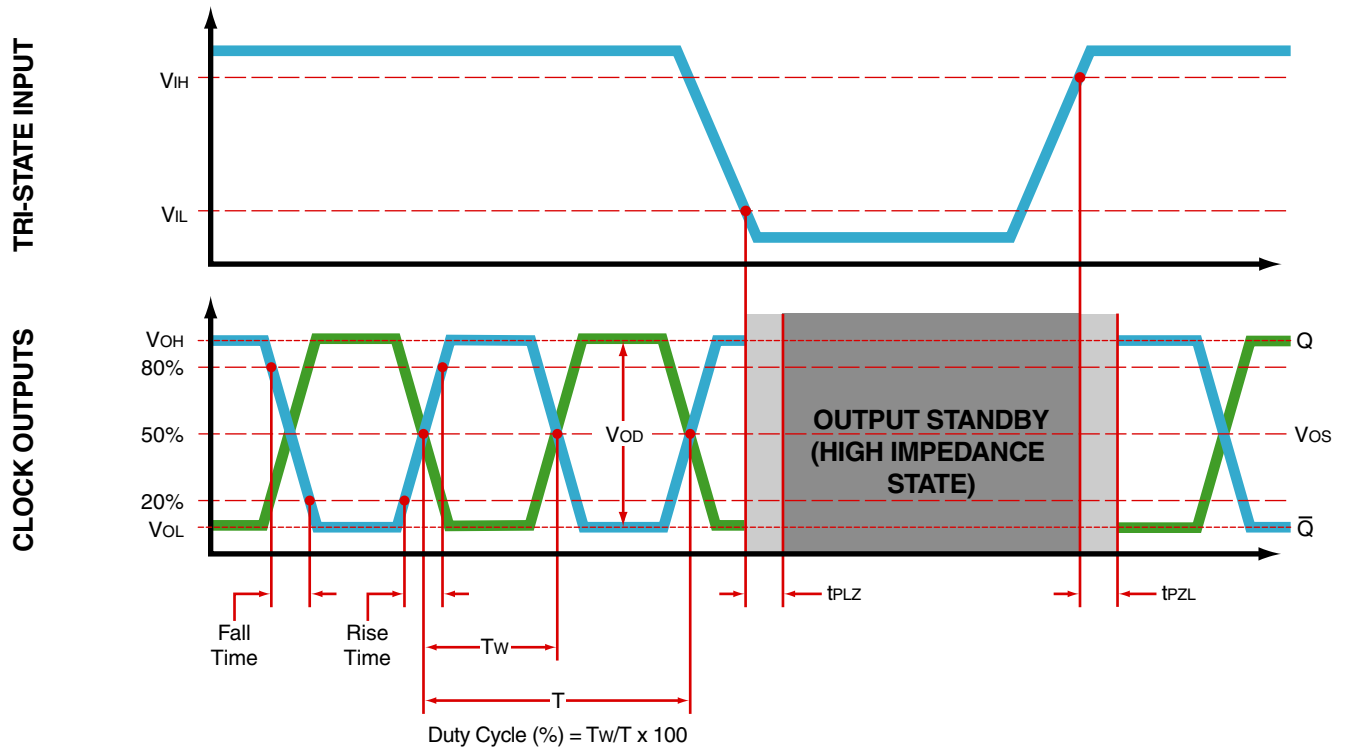
EMDS13F2H-90.000M

OUTPUT WAVEFORM & TIMING DIAGRAM



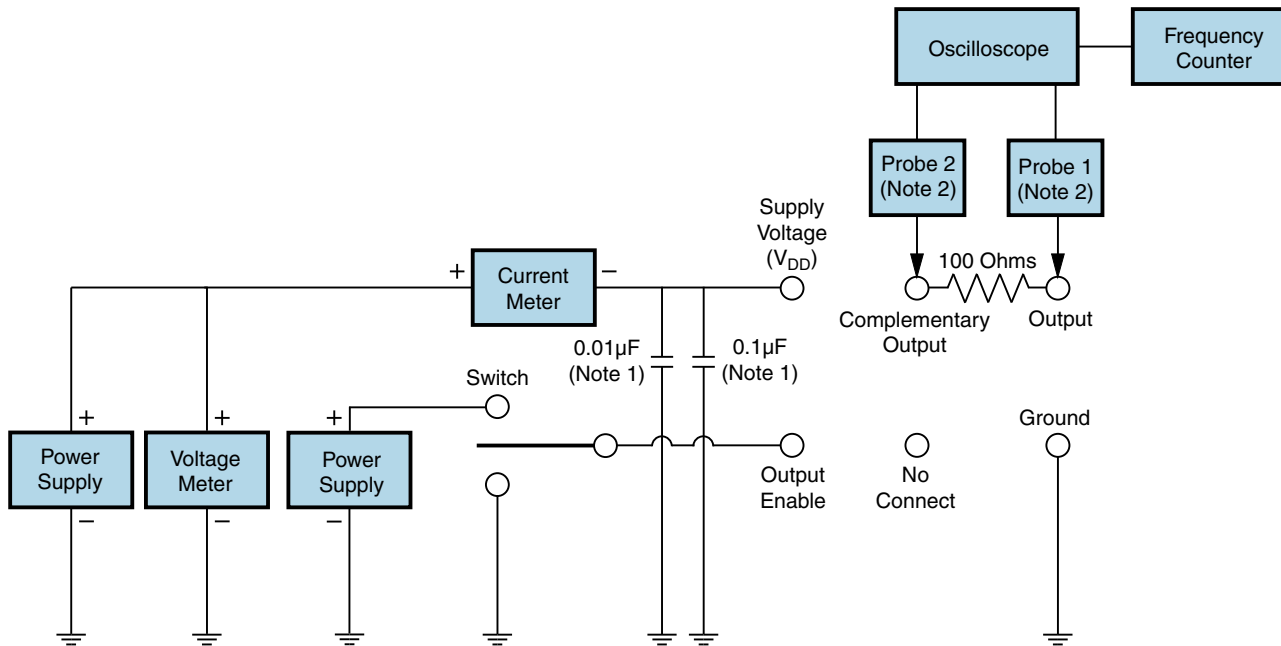
EMDS13F2H-90.000M

OUTPUT WAVEFORM & TIMING DIAGRAM



EMDS13F2H-90.000M

Test Circuit for Output Enable and Complementary Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>500MHz) passive probe is recommended.

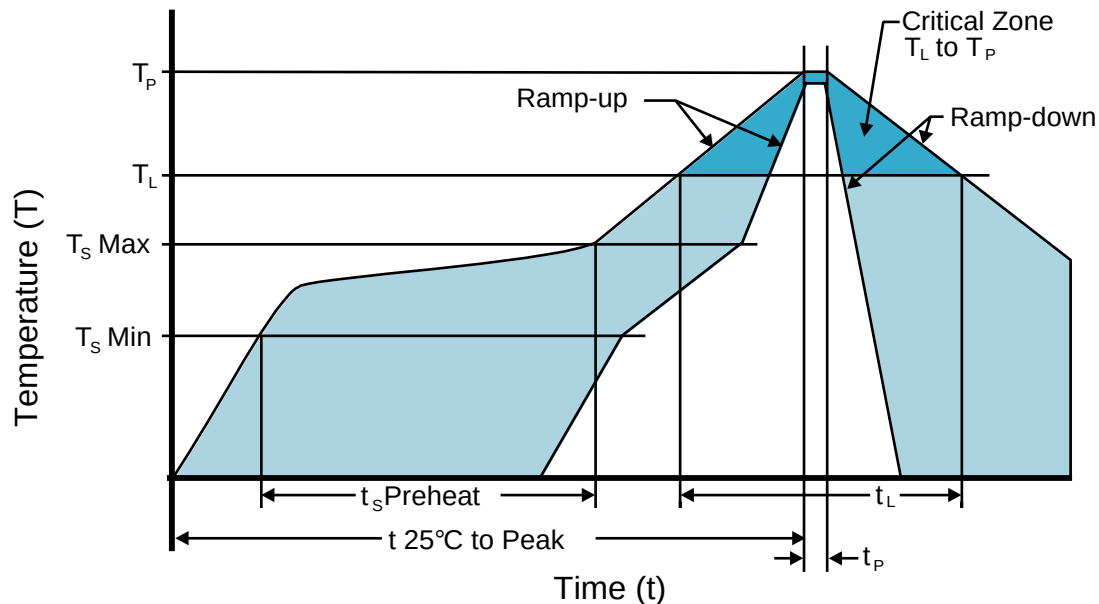
Note 3: Test circuit PCB traces need to be designed for a characteristic line impedance of 50 ohms.

The schematic diagram illustrates the experimental setup for measuring the frequency response of a common-emitter amplifier. The circuit includes the following components and connections:

- Power Supply:** A DC power supply connected to the circuit.
- Voltage Meter:** Connected in parallel with the power supply to monitor the voltage.
- Current Meter:** Connected in series with the power supply to measure the current.
- Switch:** A switch connected to the power supply, used to control the flow of current.
- Capacitors:** Two capacitors, labeled $0.01\mu\text{F}$ (Note 1) and $0.1\mu\text{F}$ (Note 1), are connected in parallel with the power supply.
- Resistor:** A 100 Ohms resistor is connected in series with the output of the amplifier.
- Output:** The output of the amplifier is connected to the 100 Ohms resistor, which is then connected to the oscilloscope.
- Oscilloscope:** The oscilloscope is used to measure the output voltage and frequency.
- Frequency Counter:** Connected to the oscilloscope to measure the frequency of the output signal.
- Ground:** The circuit is connected to ground.

Note 3: Test circuit PCB traces need to be designed for a characteristic line impedance of 50 ohms.

Recommended Solder Reflow Methods



High Temperature Infrared/Convection

T _s MAX to T _L (Ramp-up Rate)	3°C/second Maximum
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Preheat

- Temperature Minimum (T _s MIN)	150°C
- Temperature Typical (T _s TYP)	175°C
- Temperature Maximum (T _s MAX)	200°C
- Time (t _s MIN)	60 - 180 Seconds

Ramp-up Rate (T _L to T _P)	3°C/second Maximum
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Time Maintained Above:

- Temperature (T _L)	217°C
- Time (t _L)	60 - 150 Seconds

Peak Temperature (T _P)	260°C Maximum for 10 Seconds Maximum
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Target Peak Temperature (T _P Target)	250°C +0/-5°C
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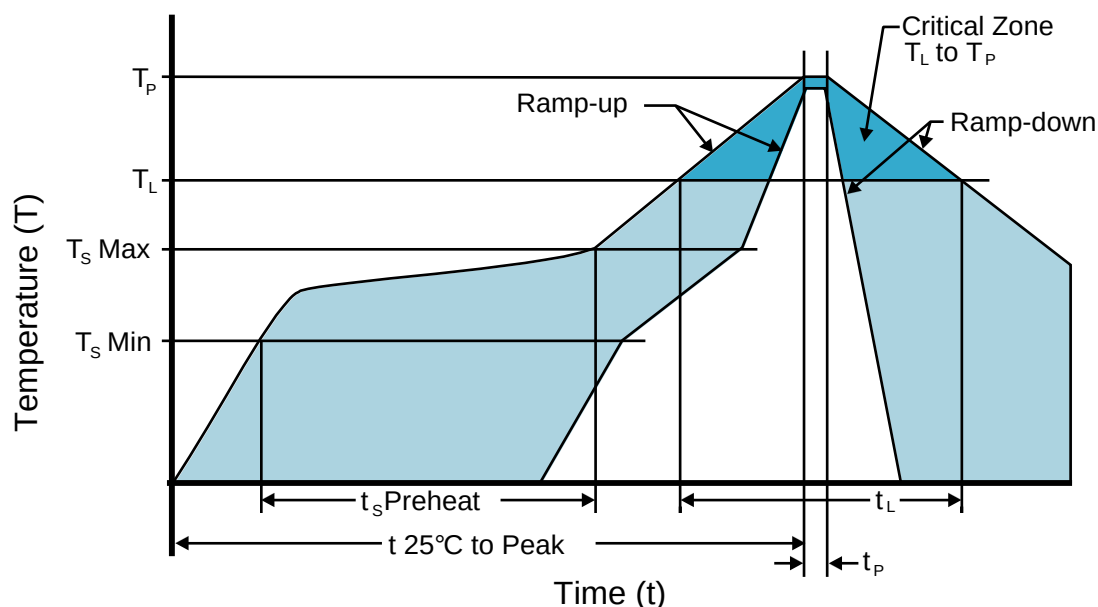
Time within 5°C of actual peak (t _p)	20 - 40 seconds
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Ramp-down Rate	6°C/second Maximum
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Time 25°C to Peak Temperature (t)	8 minutes Maximum
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Moisture Sensitivity Level	Level 1
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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

T_S MAX to T_L (Ramp-up Rate) 5°C/second Maximum

Preheat

- Temperature Minimum (T_S MIN) N/A
 - Temperature Typical (T_S TYP) 150°C
 - Temperature Maximum (T_S MAX) N/A
 - Time (t_s MIN) 60 - 120 Seconds

Ramp-up Rate (T_L to T_P) 5°C/second Maximum

Time Maintained Above:

- Temperature (T_L) 150°C
 - Time (t_L) 200 Seconds Maximum

Peak Temperature (T_P) 240°C Maximum

Target Peak Temperature (T_P Target) 240°C Maximum 2 Times / 230°C Maximum 1 Time

Time within 5°C of actual peak (t_P) 10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time

Ramp-down Rate 5°C/second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.